

1. General description

Ultrafast power diode in a TO247-2L plastic package.

2. Features and benefits

- Fast switching and soft reverse recovery characteristics
- Low forward voltage drop
- Low leakage current
- Low reverse recovery current
- Reduces switching losses in associated MOSFET or IGBT
- High operating temperature capability ($T_{j(max)} = 175^{\circ}\text{C}$)

3. Applications

- UPS
- EV Charger
- Welding Machine
- Air Conditioner

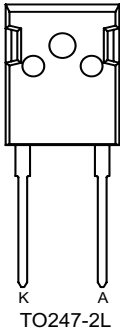
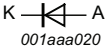
4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Values				Unit
Absolute maximum rating							
V _{RRM}	repetitive peak reverse voltage		600				V
I _{F(AV)}	average forward current	δ = 0.5 ; square-wave pulse; T _{mb} ≤ 129 °C; Fig. 1 ; Fig. 2 ; Fig. 3	60				A
I _{FRM}	repetitive peak forward current	δ = 0.5 ; t _p = 25 μs; T _{mb} ≤ 129 °C; square-wave pulse	120				A
I _{FSM}	non-repetitive peak forward current	t _p = 10 ms; T _{j(init)} = 25 °C; sine-wave pulse; Fig. 4	600				A
		t _p = 8.3 ms; T _{j(init)} = 25 °C; sine-wave pulse	660				A
Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
V _F	forward voltage	I _F = 60 A; T _j = 25 °C; Fig. 6		-	1.55	2	V
		I _F = 60 A; T _j = 150 °C; Fig. 6		-	1.2	1.6	V
Dynamic characteristics							
t _{rr}	reverse recovery time	I _F = 1 A; V _R = 30 V; dI _F /dt = 50 A/μs; T _j = 25 °C; Fig. 7		-	-	55	ns

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode		
2	A	anode		
mb	mb	mounting base; connected to cathode		

6. Ordering information

Table 3. Ordering information

Type number	Package name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
BYQ60W-600PT2	TO247-2L	BYQ60W-600PT2Q	Tube	30	TO247L-2L	10-Nov-2020

7. Marking

Table 4. Marking codes

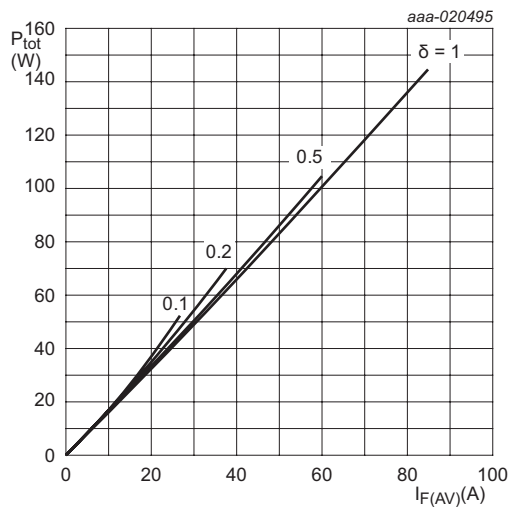
Type number	Marking codes
BYQ60W-600PT2	BYQ60W 600PT2

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

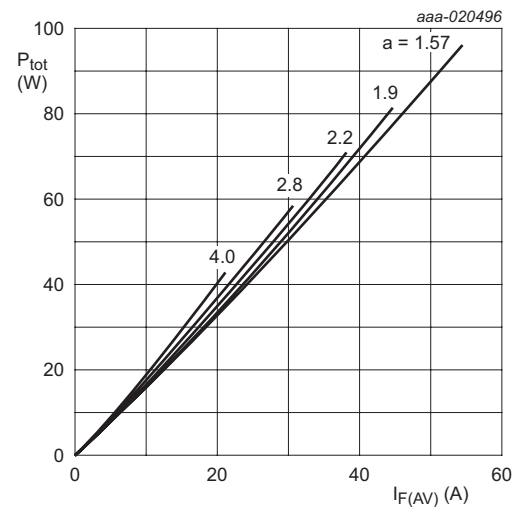
Symbol	Parameter	Conditions	Values	Unit
V_{RRM}	repetitive peak reverse voltage		600	V
V_{RWM}	crest working reverse voltage		600	V
V_R	reverse voltage	DC	600	V
$I_{F(AV)}$	average forward current	$\delta = 0.5$; square-wave pulse; $T_{mb} \leq 129^\circ\text{C}$; Fig. 1; Fig. 2; Fig. 3	60	A
I_{FRM}	repetitive peak forward current	$\delta = 0.5$; $t_p = 25\ \mu\text{s}$; $T_{mb} \leq 129^\circ\text{C}$; square-wave pulse	120	A
I_{FSM}	non-repetitive peak forward current	$t_p = 10\ \text{ms}$; $T_{j(\text{init})} = 25^\circ\text{C}$; sine-wave pulse; Fig. 4	600	A
		$t_p = 8.3\ \text{ms}$; $T_{j(\text{init})} = 25^\circ\text{C}$; sine-wave pulse	660	A
I^2t	limiting Joule-integral	SIN; $t_p = 10\ \text{ms}$	1800	A^2s
T_{stg}	storage temperature		-55 to 175	$^\circ\text{C}$
T_j	junction temperature		175	$^\circ\text{C}$



$$I_{F(AV)} = I_{F(RMS)} \times \sqrt{\delta}$$

$$V_o = 1.600\ \text{V}; R_s = 0.0013\ \Omega$$

Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values



$$a = \text{form factor} = I_{F(RMS)} / I_{F(AV)}$$

$$V_o = 1.600\ \text{V}; R_s = 0.0013\ \Omega$$

Fig. 2. Forward power dissipation as a function of average forward current; sinusoidal waveform; maximum values

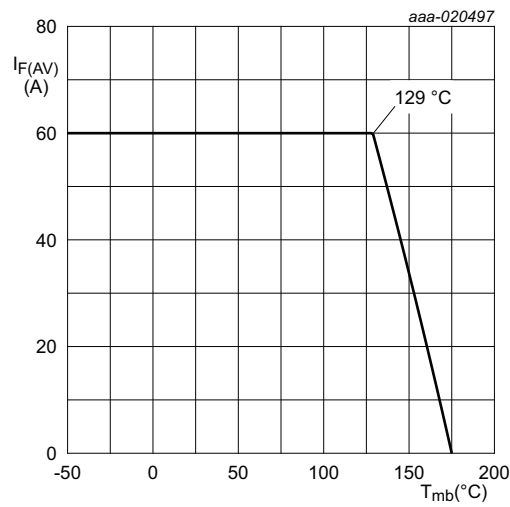


Fig. 3. Forward current as a function of mounting base temperature; maximum values

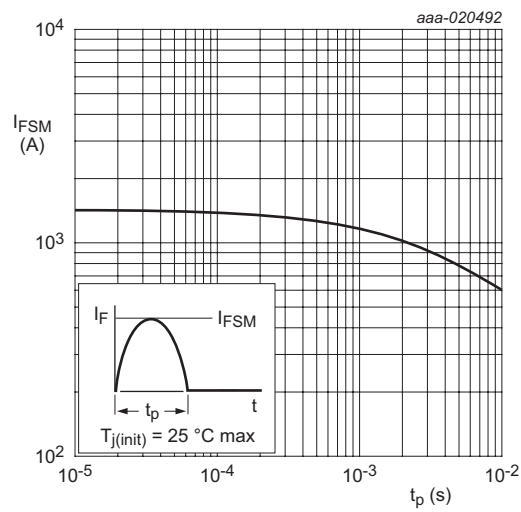


Fig. 4. Non-repetitive peak forward current as a function of pulse width; sinusoidal waveform; maximum values

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	Fig. 5	-	-	0.44	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	in free air	-	45	-	K/W

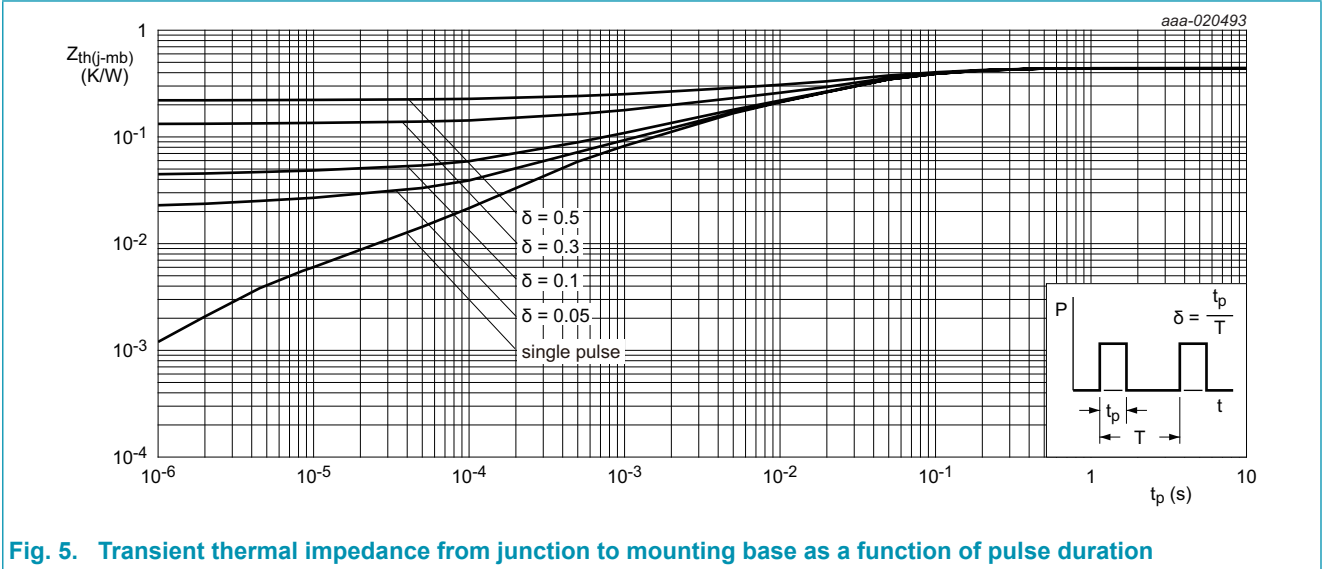
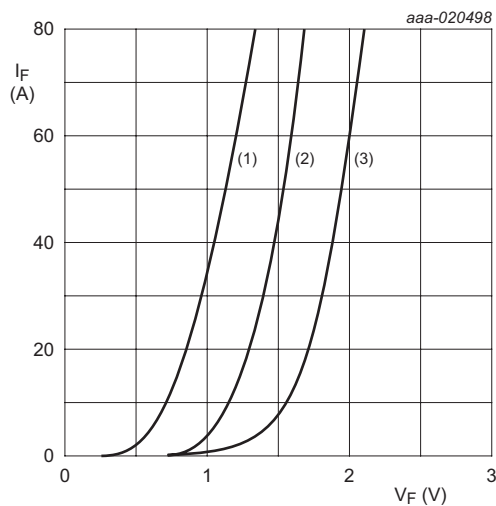


Fig. 5. Transient thermal impedance from junction to mounting base as a function of pulse duration

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
V _F	forward current	I _F = 60 A; T _j = 25 °C; Fig. 6		-	1.55	2	V
		I _F = 60 A; T _j = 150 °C; Fig. 6		-	1.2	1.6	V
I _R	reverse current	V _R = 600 V; T _j = 25 °C		-	-	10	μA
		V _R = 600 V; T _j = 125 °C		-	-	500	μA
Dynamic characteristics							
Q _r	reverse charge	I _F = 60 A; V _R = 400 V; dI _F /dt = 200 A/μs; T _j = 25 °C; Fig. 7		-	143	-	nC
		I _F = 60 A; V _R = 400 V; dI _F /dt = 200 A/μs; T _j = 125 °C; Fig. 7		-	876	-	nC
t _{rr}	reverse recovery time	I _F = 1 A; V _R = 30 V; dI _F /dt = 50 A/μs; T _j = 25 °C; Fig. 7		-	-	55	ns
		I _F = 60 A; V _R = 400 V; dI _F /dt = 200 A/μs; T _j = 25 °C; Fig. 7		-	53	-	ns
		I _F = 60 A; V _R = 400 V; dI _F /dt = 200 A/μs; T _j = 125 °C; Fig. 7		-	120	-	ns
I _{RM}	peak reverse recovery current	I _F = 60 A; V _R = 400 V; dI _F /dt = 200 A/μs; T _j = 25 °C; Fig. 7		-	5.4	-	A
		I _F = 60 A; V _R = 400 V; dI _F /dt = 200 A/μs; T _j = 125 °C; Fig. 7		-	14.5	-	A



$V_o = 1.600 \text{ V}; R_s = 0.0013 \text{ } \Omega$

(1) $T_j = 150 \text{ }^\circ\text{C}$; typical values

(2) $T_j = 150 \text{ }^\circ\text{C}$; maximum values

(3) $T_j = 25 \text{ }^\circ\text{C}$; maximum values

Fig. 6. Forward current as a function of forward voltage

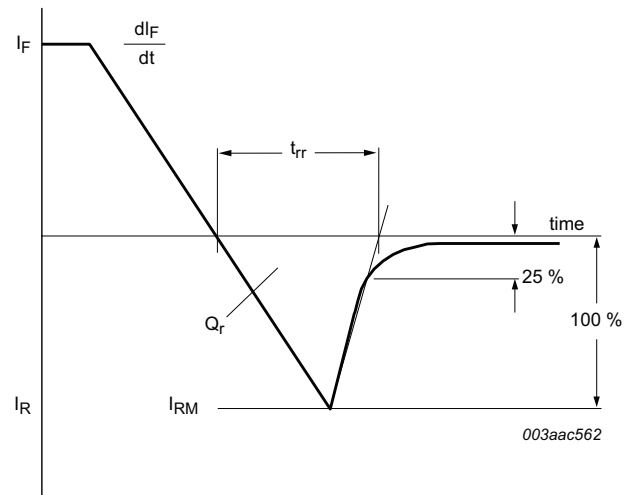


Fig. 7. Reverse recovery definitions; ramp recovery

11. Package outline

Plastic single-ended through-hole package; heatsink mounted;1 mounting hole; 2 leads TO-247

TO247-2L

The technical drawing illustrates the package outline of the BYQ60W-600PT2 ultrafast power diode. It includes three views: a top view, a side view, and a front view. The top view shows the overall dimensions E (width) and D (height), with mounting holes of diameter Ø. The side view shows the lead length L, lead diameter b, and lead spacing e. The front view shows the lead diameter b1, lead spacing b, and lead length L1. The package is a plastic single-ended through-hole package, heatsink mounted, with 1 mounting hole and 2 leads TO-247.

UNIT	A	A ₁	b	b ₁	c	D	D ₁	D ₂	E	E ₁	E ₂	E ₃	e	L	L ₁	P ₂	p	Q	q	Ø
mm	5.20	2.10	1.40	2.20	0.70	20.60	16.20	1.20	15.75	14.22	5.20	1.80	10.90	20.72	4.75	3.60	3.70	2.60	6.18	7.30
	4.70	1.90	1.00	1.80	0.50	20.30	16.87	0.80	15.45	13.82	4.80	1.40	BSC	20.22	4.25	3.40	3.50	2.20	5.78	7.10

Note:

- Mold resin protrusion max 0.127mm.
- Metal exposed with Sn plating.

12. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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- [2] The term 'short data sheet' is explained in section "Definitions".
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13. Contents

1. General description.....	1
2. Features and benefits	1
3. Applications	1
4. Quick reference data.....	1
5. Pinning information.....	2
6. Ordering information.....	2
7. Marking.....	2
8. Limiting values	3
9. Thermal characteristics	5
10. Characteristics.....	6
11. Package outline	7
12. Legal information	8
13. Contents	10

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